Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

/!\ REMINDERS

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Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact Taiyo Yuden Co., Ltd. for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
- All electronic components or functional modules listed in this catalog are developed, designed and intended for use in general electronics equipment.(for AV, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.). Before incorporating the components or devices into any equipment in the field such as transportation,(automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance.

Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

- The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN's official sales channel"). It is only applicable to the products purchased from any of TAIYO YUDEN's official sales channel.
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Certain items in this catalog may require specific procedures for export according to "Foreign Exchange and Foreign Trade Control Law" of Japan, "U.S. Export Administration Regulations," and other applicable regulations. Should you have any question or inquiry on this matter, please contact our sales staff.

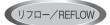
Should you have any question or inquiry on this matter, please contact our sales staff.

SMD インダクタ(コンパクトタイプ) SMD INDUCTORS COMPACT TYPE



OPERATING TEMP.

-25~+105℃ (製品自己発熱含む) (Including self-generated heat)



特長 FEATURES

- ・BRC 2016/BRL 3225 (新製品) 一面電極構造採用により、最大効率設計を実現しました。 DC/DCコンバータなどの大電流を必要とする、回路設計に適した小型・ 低背型チップインダクタです。
- BRC 2016/BRL 3225 (NEW PRODUCTS)

 The best efficiency design is achieved by adopting bottom-surface electrode structure. Small and low-profile Wound Chip Inductors that are suit for module design which needs high electric current like DC/DC convert-

用途 APPLICATIONS

・携帯電話、HDD、DVC、DSC、PDA、液晶ディスプレイ等の小型DC/DC コンバータ用途 For small DC/DC converter (cellular phone, HDD,DVC, DSC, PDA, LCD display etc).

形名表記法 ORDERING CODE



形式	
BR	SMDインダクタ

3

外形寸法(W	/×L) : mm(inch)
1608 (0603)	1.6×0.8 mm
2012(0805)	2.0×1.2 mm
2016 (0806)	2.0×1.6 mm
2518 (1007)	2.5×1.8 mm
3225(1210)	3.2×2.5 mm

A

公称インダクタンス[µH]	
例	
R20	0.2
1R0	1.0
2R2	2.2
4R7	4.7

6

インダ	「クタンス許容差
М	±20%
K	±10%

2

特性化	±様
\triangle	低Rdc
L	低背
С	大電流

4

包装	
Т	テーピング

7

当社管	理番号		
$\triangle\triangle\triangle$	標準	4	
			=

△=スペース

B, R, \triangle , 2, 5, 1, 8, T, 2, R, 2, M, \triangle , \triangle , \triangle



Туре	
BB	SMD Inductors

外形寸法(V	V×L) : mm(inch)
1608 (0603)	1.6×0.8 mm
2012(0805)	2.0×1.2 mm
2016 (0806)	2.0×1.6 mm
2518 (1007)	2.5×1.8 mm
3225(1210)	3.2×2.5 mm

5

Nominal Inductance (µH)	
example	
R20	0.2
1R0	1.0
2R2	2.2
4R7	4.7

6

Inductance tolerance	
М	±20%
K	±10%

2

Characteristic Spec	
L	Low profile
С	High Current

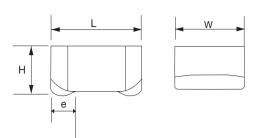
4

Packa	ging		
T		Tape and Reel	



Interna	al code
\triangle	Standard product
	∧ — DI==I- C==

△=Blank Space



				Unit: mm(inch)
Type	L	W	Н	е
BR C1608	1.6±0.2 (0.063±0.008)	0.8±0.2 (0.031±0.008)	0.8±0.2 (0.031±0.008)	0.45±0.15 (0.016±0.006)
BR L2012	2.0±0.2 (0.078±0.008)	1.25±0.2 (0.049±0.008)	1.0 max (0.040 max)	0.5±0.2 (0.020±0.008)
BR C2016	2.0±0.2 (0.078±0.008)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	0.5±0.2 (0.020±0.008)
BR L2518	2.5±0.2 (0.098±0.008)	1.8±0.2 (0.071±0.008)	1.2 max (0.048 max)	0.5±0.2 (0.020±0.008)
BR L3225	3.2±0.2 (0.126±0.008)	2.5±0.2 (0.098±0.008)	1.7 max (0.068 max)	0.75±0.2 (0.03±0.008)

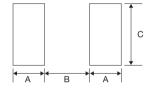
推奨ランド Recommended Land Patterns

実装上の注意

- ・実装状態を確認の上ご使用下さいますようお願いいたします。
- ・本製品のはんだ付けはリフローはんだ工法に限ります。

Surface Mounting

- · Mounting and soldering conditions should be checked beforehand.
- · Applicable soldering process to this products is reflow soldering only.



			Unit : mm
Туре	A	В	С
1608	0.55	0.80	1.00
2012	0.65	0.90	1.40
2016	0.70	0.80	1.80
2518	0.65	1.50	1.95
3225	1.00	1.60	2.70

概略バリエーション AVAILABLE INDUCTANCE RANGE

	Туре										
Range	Туре	BR L3225		BR L	.2518	BR C	22016	BR L	2012	BR C1608	
		Imax[mA]	Rdc±30%[Ω]	Imax[mA]	Rdc±30%[Ω]	Imax[mA]	Rdc±30%[Ω]	Imax[mA]	Rdc±30%[Ω]	Imax[mA]	Rdc±30%[Ω]
								1,050	7μH 0.090	980 0.2	μH 0.060
		2.200	1μH 0.043	1,000	ιΗ 0.080	1,100	μΗ 0.085	850	0.135	520	0.180
	1.0	2,200	0.040	850	0.135	1,100	0.085	830	0.135	280	0.550
	2.2									2.2	
	4.7			470	0.400						
ΉH		700	0.350	4.7μ	ιH	520	0.400	270	0.850		
]eo	10	700	0.350						0.650		
tar	22										
${\sf Inductance}[\mu{\sf H}]$	47										
<u>-</u>	100	250	2.50								
	100	10	 0μΗ			170	3.40	85	7.70		
	220					100μH		100	lμH		
		Imax	Rdc±20%	Imax	Rdc±30%	lmax	Rdc±30%	Imax	Rdc±30%	Imax	Rdc±30%
es es	Inductance	(mA)	(Ω)	(mA)	(Ω)	(mA)	(Ω)	(mA)	(Ω)	(mA)	(Ω)
代表值 Examples	1μΗ	2,200(1.0μH) 0.043(1.0μH)	1,000(1.0μH)	0.080(1.0µH)	1,100(1.0µH)	0.085(1.0μH)	1050(0.47μH)	0.090(0.47µH)	980(0.20μH)	0.060 (0.20 µH)
Exa	2.2μΗ	700(10μH)	0.350(10 µ H)	850 (2.2 μH)	0.135(2.2µH)	520(10μH)	0.400(10μH)	270(10µH)	0.850(10µH)	520 (1.0 μ H)	0.180 (1.0 μH)
	4.7μH	250(100μH)	2.50(100 µH)	470 (4.7μH)	0.400(4.7µH)	170(100 µ H)	3.40(100 µH)	85(100 µH)	7.70(100 µH)	280(2.2μH)	0.550(2.2µH)

セレクションガイド Selection Guide













アイテム一覧 PART NUMBERS

BR C1608 type -

BR Cloub type										
形名		EHS (Environmental	公称 インダクタンス	インダクタンス 許容差	自己共振 周波数 Self-resonant	直流抵抗 DC Resistance		፤流※) current iA]	測定 周波数 Measuring	
Ordering code		Hazardous Substances)	Inductance [μH]	Inductance Tolerance	frequency [MHz] min	[Ω] (±30%)	直流重畳許容電流 Saturation current Idc1	温度上昇許容 Temperature rise current Idc2	frequency [MHz]	
BR C1608TR20M		RoHS	0.20		400	0.060	1750	980		
BR C1608TR35M		RoHS	0.35		300	0.080	1400	810		
BR C1608TR45M		RoHS	0.45		200	0.090	1250	800		
BR C1608TR56M		RoHS	0.56	±20%	170	0.095	1150	760	7.96	
BR C1608TR77M		RoHS	0.77	±20%	150	0.110	1000	660	7.96	
BR C1608T1R0M		RoHS	1.00		140	0.180	850	520		
BR C1608T1R5M		RoHS	1.50		120	0.300	700	410		
BR C1608T2R2M		RoHS	2.20		100	0.550	550	280		

BR L2012 type -

BH LZ012 type								
形名	EHS (Environmental	公称 インダクタンス	インダクタンス 許容差	自己共振 周波数 Self-resonant	直流抵抗 DC Resistance	Rated	ī流※) current nA]	測定 周波数 Measuring
Ordering code	Hazardous Substances)	Inductance [µH]	Inductance Tolerance	frequency [MHz] min	[Ω] (±30%)	直流重畳許容電流 Saturation current Idc1	温度上昇許容 Temperature rise current Idc2	frequency [MHz]
BR L2012TR47M	RoHS	0.47		350	0.090	1,100	1,050	
BR L2012T1R0M	RoHS	1.0		300	0.135	850	850	
BR L2012T1R5M	RoHS	1.5		250	0.180	700	750	
BR L2012T2R2M	RoHS	2.2		200	0.300	600	550	7.96
BR L2012T3R3M	RoHS	3.3		190	0.500	490	440	
BR L2012T4R7M	RoHS	4.7		150	0.550	340	400	
BR L2012T6R8M	RoHS	6.8	±20%	60	0.750	290	350	
BR L2012T100M	RoHS	10	120%	30	0.850	270	330	
BR L2012T150M	RoHS	15		15	1.00	220	300	
BR L2012T220M	RoHS	22		13	1.30	190	270	2.52
BR L2012T330M	RoHS	33		8.0	2.00	150	220	2.32
BR L2012T470M	RoHS	47		7.0	3.50	125	160	
BR L2012T680M	RoHS	68		6.5	5.80	100	110	
BR L2012T101M	RoHS	100		6.0	7.70	85	85	0.796

BR C2016 type

BR C2016 type ————————————————————————————————————									
形名		EHS (Environmental	公称 インダクタンス	インダクタンス 許容差	自己共振 周波数 Self-resonant	直流抵抗 DC	定格電流※) Rated current [mA]		測定 周波数 Measuring
Ordering code		Hazardous Substances)	Inductance [μH]	Inductance Tolerance	frequency [MHz] min	Resistance $[\Omega]$ $(\pm 30\%)$	直流重畳許容電流 Saturation current Idc1	温度上昇許容 Temperature rise current Idc2	frequency [MHz]
BR C2016T1R0M		RoHS	1.0		450	0.085	1,350	1,100	
BR C2016T1R5M		RoHS	1.5		370	0.150	1,100	820	
BR C2016T2R2M		RoHS	2.2	±20%	250	0.180	910	760	
BR C2016T3R3M		RoHS	3.3	±20%	140	0.220	740	680	
BR C2016T4R7M		RoHS	4.7		78	0.270	660	610	
BR C2016T6R8M		RoHS	6.8		39	0.330	550	560	
BR C2016T100□		RoHS	10		35	0.400	450	520	0.10
BR C2016T150		RoHS	15		28	0.600	400	410	
BR C2016T220□		RoHS	22	1.000/	24	1.00	310	310	
BR C2016T330		RoHS	33	±20% ±10%	13	1.70	270	240	
BR C2016T470		RoHS	47	±10%	11	2.20	210	210	
BR C2016T680		RoHS	68		8	2.80	200	190	
BR C2016T101		RoHS	100		7	3.40	140	170	

(注)形名の□にはインダクタンス許容差記号 (MまたはK)が入ります。

[·] Please specify the inductance tolerance code. (M or K)

[※])直流重畳許容電流 (Idc1) は、直流重畳によるインダクタンス低下が-30%以内となる直流電流値 (at 20%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

^{※)} 温度上昇許容電流 (Idc2) は、温度上昇が40℃となる直流電流値 (at 20℃) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

^{※)}定格電流値は直流重畳許容電流、または温度上昇許容電流をいずれも満足する直流電流値 The rated current is the DC current value that satisfies both of DC saturation current value and temperature rise current value.

アイテム一覧 PART NUMBERS

BB I 2518 type -

Bh E2516 type										
形名 Ordering code		EHS (Environmental Hazardous Substances)	公称 インダクタンス Inductance [μH]	インダクタンス 許容差 Inductance Tolerance	自己共振 周波数 Self-resonant frequency [MHz] min	直流抵抗 DC Resistance [Ω] (±30%)	定格電 Rated ([m 直流重畳許容電流 Saturation current Idc1	current A] 温度上昇許容	測定 周波数 Measuring frequency [MHz]	
BR L2518T1R0M		RoHS	1.0		130	0.080	1600	1000		
BR L2518T1R5M		RoHS	1.5		100	0.100	1200	920		
BR L2518T2R2M		RoHS	2.2	±20%	80	0.135	1000	850	7.96	
BR L2518T3R3M		RoHS	3.3		70	0.300	800	580		
BR L2518T4R7M		RoHS	4.7		60	0.400	700	470		

BR I 3225 type -

BR L3225 type										
形名 Ordering code		EHS (Environmental Hazardous Substances)	公称 インダクタンス Inductance [μH]	インダクタンス 許容差 Inductance Tolerance	自己共振 周波数 Self-resonant frequency [MHz] min	直流抵抗 DC Resistance [Ω] (±20%)	[m 直流重畳許容電流	配流※) current nA] 温度上昇許容 Temperature rise current Idc2	測定 周波数 Measuring frequency [MHz]	
BR L3225T1R0M		RoHS	1.0		220	0.043	2,400	2,200		
BR L3225T2R2M		RoHS	2.2	±20%	150	0.065	1,850	1,600		
BR L3225T4R7M		RoHS	4.7		120	0.180	1,300	1,000		
BR L3225T100		RoHS	10		70	0.350	900	700	0.10	
BR L3225T220		RoHS	22	±20%	50	0.690	550	470		
BR L3225T470		RoHS	47	±10%	40	1.00	420	390		
BR L3225T101		RoHS	100		30	2.50	270	250		

⁽注)形名の□にはインダクタンス許容差記号 (MまたはK)が入ります。

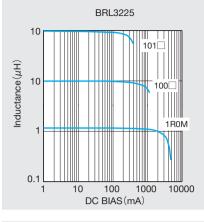
 $[\]cdot$ Please specify the inductance tolerance code. (M or K)

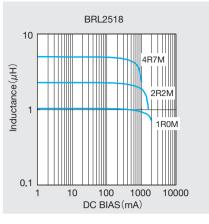
^{※)} 直流重畳許容電流 (Idc1) は、直流重畳によるインダクタンス低下が-30%以内となる直流電流値 (at 20℃) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

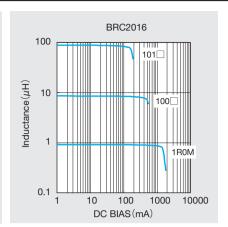
^{※)} 温度上昇許容電流 (Idc2) は、温度上昇が40℃となる直流電流値 (at 20℃) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40°C. (at 20°C)

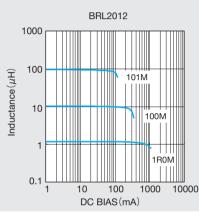
^{※)} 定格電流値は直流重畳許容電流、または温度上昇許容電流をいずれも満足する直流電流値 The rated current is the DC current value that satisfies both of DC saturation current value and temperature rise current value.

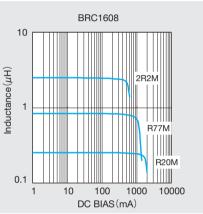
直流重畳特性例 DC Bias characteristics (Measured by HP4285A)



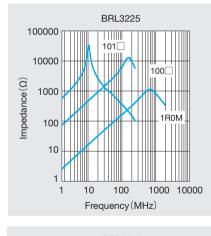


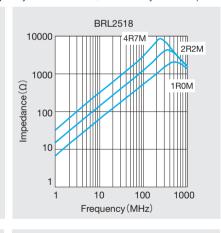


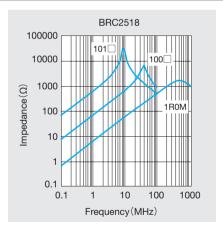


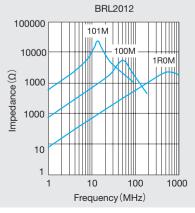


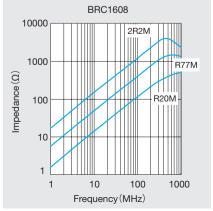
インピーダンス周波数特性 Impedance-vs-Frequency characteristics (Measured by HP4291A)









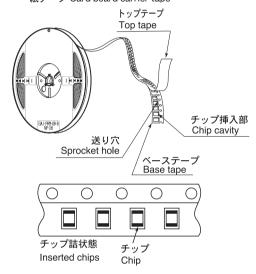


①最小受注単位数 Minimum Quantity

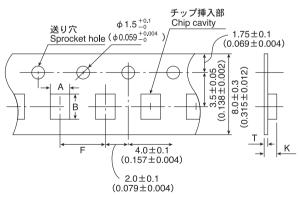
型式	標準数量[個] Standard Quantity[pcs]				
Туре	紙テーピング Paper Tape	エンボステーピング Embossed Tape			
BR C1608	_	3000			
BR L2012	_	3000			
BR C2016	_	2000			
BR L2518	_	3000			
BR L3225	_	2000			

②テーピング材質 Tape Material

エンボステープ Embossed tape 紙テープ Card board carrier tape



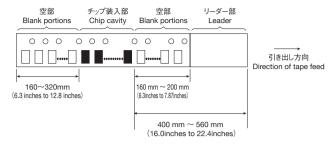
③テーピング寸法 Taping dimensions エンボステーブ (8mm幅) Embossed Tape (0.315 inches wide) 紙テープ (8mm幅) Card board carrier tape (0.315 inches wide)



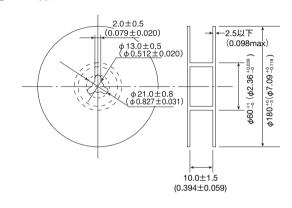
形式 Type	チップ Chip		挿入ピッチ Insertion pitch	テープ厚み Tape thickness		
	Α	В	F	Т	K	
BR C1608	1.1±0.5	1.9±0.5	4.0±0.1	0.25±0.05	1.35max	
	(0.04±0.002)	(0.076±0.002)	(0.157±0.004)	(0.01±0.002)	(0.054)	
BR L2012	1.40±0.1	2.20±0.1	4.0±0.1	0.25±0.05	1.2max	
	(0.056±0.004)	(0.088±0.004)	(0.157±0.004)	(0.01±0.002)	(0.048)	
BR C2016	1.9 ± 0.2	2.2 ± 0.2	4.0 ± 0.1	0.3 ± 0.05	2.15MAX	
	(0.075 ± 0.008)	(0.087 ± 0.008)	(0.157 ± 0.004)	(0.012 ± 0.002)	(0.085MAX)	
BR L2518	2.3±0.2	2.8±0.2	4.0±0.1	0.3±0.05	1.5 max	
	(0.092±0.008)	(0.112±0.008)	(0.157±0.004)	(0.012±0.002)	(0.060)	
BR L3225	2.8 ± 0.1	3.5 ± 0.1	4.0 ± 0.1	0.25 ± 0.05	1.75 MAX	
	(0.112 ± 0.004)	(0.140 ± 0.004)	(0.157 ± 0.004)	(0.01 ± 0.002)	(0.075)	

Unit: mm(inch)

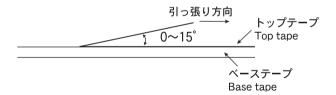
④リーダー部・空部 Leader and Blank portion



⑤リール寸法 Reel size



⑥トップテープ強度 Top Tape Strength トップテープのはがし力は、下図矢印方向にて0.2~0.7Nとなります。 The top tape requires a peel-off force of 0.2 to 0.7N in the direction of the arrow as illustrated below.



		Specifled Value					
Item	BRC1608, BRL2012, BRC2016, BRL2518, BRL3225 Type	NRH24, NR30/40/60/80, NRG40 Type	NR10050 Type		Test Method	and Remarks	
1.Operating Temperature Range	-25°C∼+105°C	-25°C∼+120°C	-25°C∼+105°C	Inc	cluding self-generated hea	ıt	
2.Storage Temperature Range	-40°C∼+85°C				BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type, IRH24, NR30/40/60/80, NRG4026Type : 0 to 40°C for the product with taping.		
3.Rated current	Within the specified tolerance			The with	R10050 Type: 0 ~40°C for e maximum DC value havithin specified value and te °C by the application of Di ductance decrease BRC1608,BRL2012,BRC201 NRH24, NR30/40/60/80,NR	ing inductance decrease imperature increase within C bias. 6,BRL2518, BRL3225Type,	
4.Inductance				NR L	30% BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type LCR Meter : HP 4285A or equivalent, Measuring frequency:Specified frequency NRH24, NR30/40/60/80, NRG4026Type : LCR Meter : HP 4285A or equivalent, 100KHz, 1V NR10050Type : LCR Meter : HP 4263A or equivalent, 100KHz, 1V		
5.DC Resistance	Within the specified tolerance				ohmmeter : HIOKI 3227		
6.Self resonance frequency	Within the specification			NR Ir	C1608,BRL2012,BRC2016,BI IH24, NR30/40/60/80Type, NR npedance analyzer/material ar IP4191A, 4192A or equivaler	110050Type: nalyzer: HP4291A or equivalent	
7.Temperature characteristic	BRL2012, BRC2016, BRL2518, BRL3225 Inductance change : Within±15% BRC1608 Inductance change : Within±20%	Inductance change : Within±20%		NR N r V	range within $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$ Vith reference to inductance shall be calculated.	26Type , NR10050Type: shall be taken at temperature	
8.Resistance to flexure of			Λ		Temperature at step 3 Temperature at step 4 Temperature st step 5	20°C (Standard temperature) Maximum oparating temperature 20°C	
8. Hesistance to flexure of substrate	No damage.			NF The Assinct Test Sold	illustrated below, apply forcificating until deflection of the toard size: 100×40×1.0 Test it der cream thickness: 0.15(BR Ser 0.10(NR Ser	G4026Type: ad to the test board by the reflow. the in the direction of the arrow the test board reaches to 2 mm. board material: glass epoxy-resin ties)	
9.Insulation resistance : between wires					1. 3 <u>r</u> 3 0		
10.Insulation resistance : between wire and core				1			
11.Withstanding voltage: between wires and core							
permeen miles and cole		TAIVO VIID					

		Specifled Value		
12.Adhesion of terminal Item electrode	BRC1608, BRL2012, BRC2016, BRL2518, BRL3225 Type	NRH24, NR30/40/60/80, NRG40 Type	NR10050 Type	Test Method and Remarks
	Shall not come off PC board.			BRC1608,BRL2012,BRC2016,BRL2518, BRL3225Type, NRH24, NR30/40/60/80, NRG40Type: The test samples shall be soldered to the test board by the reflow. pplied force: 10N to X and Y directions. Duration: 5s. Solder cream thickness: 0.15mm. NR10050Type: Applied force: 5N to X and Y directions. Duration: 5s.
13.Resistance to vibration	Inductance change: Within±10° No significant abnormality in app			BRC1608,BRL2012,BRC2016,BRL2518, BRL3225Type, NRH24, NR30/40/60/80, NRG40Type, NR10050Type: The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions. Frequency Range 10~55Hz Total Amplitude 1.5mm (May not exceed acceleration 196 m/S²) Sweeping Method 10Hz to 55Hz to 10 Hz for 1 min. X Time X Y Z For 2 hours on each X, Y, and Z axis. Recovery: At least 2hrs of recovery under the standard condition sfter the test, followed by the measurement within 48 hrs.
14.Solderability	At least 90% of surface of termin covered by new solder.	nal electrode is		BRC1608,BRL2012,BRC2016,BRL2518, BRL3225Type, NRH24, NR30/40/60/80, NRG40Type, NR10050Type: The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table Flux: Methanol solution containing rosin 25%. NRH24, NR30/40/60/80Type,NR10050 Type: Solder Temperature 245±5°C Time 5±1.0sec BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type: Solder Temperature 245±5°C Time 5±0.5sec **Immersion depth: All sides of mounting terminal shall be immersed.

		Specifled Value		
ltem	BRC1608, BRL2012, BRC2016, BRL2518, BRL3225 Type	NRH24, NR30/40/60/80, NRG40 Type	NR10050 Type	Test Method and Remarks
15 Desistance to coldering	Industrance change: Within ± 10	0/		PPC1609 PPI 2012 PPC2016 PPI 2619 PPI 2225T/mg :
15.Resistance to soldering heat	Inductance change: Within±10' No significant abnormality in app			BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type: 3 times of reflow oven at 230°CMIN for 40 sec. with peak temperature at 260 $^{+6}_{-0}$ °C for 5 sec. NRH24, NR30/40/6012 · 6028 · 6045/80, NRG40Type, NR10050 Type: The test sample shall be exposed to reflow oven at 230±5°C for 40 seconds, with peak temperature at 260±5°C for 5 seconds, 2 times. NR6020Type: The test sample shall be exposed to reflow oven at 230±5°C for 40 seconds, with peak temperature at 250 $^{+6}_{-0}$ °C for 40 seconds, with peak temperature at 250 $^{+6}_{-0}$ °C for 5 seconds, 2 times. Test board thickness: 1.0 mm Test board material: glass epoxy-resin
16.Thermal shock	Inductance change: Within±10' No significant abnormality in app			BRC1608,BRL2012,BRC2016,BRL2518, BRL3225Type, NRH24, NR30/40/60/80, NRG40Type, NR10050 Type: The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of 1 cycle Step Temperature (°C) Duration (min) 1
17.Damp heat	Inductance change: Within±10' No significant abnormality in app			BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type: Temperature 60±2°C Humidity 90~95%RH Time 1000 hours. Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs. NRH24, NR30/40/60/80, NRG40Type: The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. Temperature 60±2°C Humidity 90~95%RH Time 500±24hour

		Specifled Value		
Item	BRC1608, BRL2012, BRC2016, BRL2518, BRL3225 Type	NRH24, NR30/40/60/80, NRG40 Type	NR10050 Type	Test Method and Remarks
18.Loading under damp	Inductance change: Within±109	%		BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type:
heat	No significant abnormality in app			Temperature 60±2°C Humidity 90~95%RH Applied current Rated current Time 1000hours. Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measuremen within 48 hrs.
				NRH24, NR30/40/60/80, NRG40Type, NR10050 Type: The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic over set at specified temperature and humidity and applied the rated current continuously as shown in below table. Temperature 60±2°C Humidity 90~95%RH Applied current Rated current Time 500±2hour
19.Low temperature life test	Inductance change: Within±10° No significant abnormality in apport			BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type: Temperature
				NRH24, NR30/40/60/80, NRG40Type, NR10050 Type: The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table. Temperature -40±3°C Time 500±24hour
20.High temperature life test	Inductance change: Within±10% No significant abnormality in appearance.		Inductance change: Within±10% No significant abnormality in appearance.	BRC1608,BRL2012,BRC2016,BRL2518,BRL3225Type: Temperature 85±2°C Duration 1000hours Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measuremen within 48 hrs. NR10050 Type: Temperature 105±3°C Time 500±24hour Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measuremen
21.Loading at high		Inductance change :		within 48 hrs. NRH24, NR30/40/60/80, NRG40Type:
temperature life test		Within±10% No significant abnormality in appearance.		The test samples shall be soldered to the test board by the reflow soldering Temperature 85±2°C Applied current Rated current Time 500±24hour
22.Standard condition	Standard test condition: Unles relative humidity. When there are question concern test shall be condition of 20±2°C Inductance is in accordance with	ing measurement result : In orde	er to provide correlation date, the	

SMD Inductors

Stages	Precautions	Technical considerations		
1.Circuit Design	Operating environment, 1.The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems), where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.			
2.PCB Design	Land pattern design 1.Please refer to a recommended land pattern.	Surface Mounting Mounting and soldering conditions should be checked beforehand. Applicable soldering process to this products is reflow soldering only.		
Considerations for automatic placement	Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.	When installing products, care should be taken not to apply distortion stress as imay deform the products.		
4.Soldering	Reflow soldering 1.Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. 2.This products is reflow soldering only. 3.Please do not add any stress to a product until it returns in normal temperature after reflow soldering. Lead free soldering 1.When using products with lead free soldering, we request to use them after confirming of adhesion, temperature of resistance to soldering heat, soldering etc sufficiently. Recommended conditions for using a soldering iron: (NR10050 type) Put the soldering iron on the land-pattern. Soldering iron's temperature - Below 350 °C Duration - 3 seconds or less The soldering iron should not directly touch the inductor.	1.If products are used beyond the range of the recommended conditions, heat stresse may deform the products, and consequently degrade the reliability of the products. [BRC1608, BRL2012, BRL2518, BRC2016, BRL3225Type] Recommended reflow condition (Pb free solder) Second Secon		
5.Cleaning	Cleaning conditions 1.Washing by supersonic waves shall be avoided.	1.If washing by supersonic waves, supersonic waves may cause broken products.		
6.Handling	Handling 1.Keep the product away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations) 1.When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. 2.Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations 1.Please do not give the product any excessive mechanical shocks. 2.Please do not add any shock and power to a product in	1.Planning pattern configurations and the position of products should be careful performed to minimize stress. 1.There is a case to be damaged by a mechanical shock. 2.There is a case to be broken by the handling in transportation.		
	transportation. Pick-up pressure 1.Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. Packing	Damage and a characteristic can vary with an excessive shock or stress.		
	1.Please avoid accumulation of a packing box as much as possible.	1.There is a case that transformation and a product of tape are damaged taccumulation of a packing box.		
7.Storage conditions	Storage 1.To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions Ambient temperature 0~40°C Humidity Below 70% RH The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within 6 months from the time of delivery. In case of storage over 6 months, solderability shall be	1.Under a high temperature and humidity environment, problems such as reduce solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.		